



New Insights into Microwave Sensor Design and Applications

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Message from the Guest Editors

Dear Colleagues,

This Special Issue is devoted to collect high-quality research articles with new insights into microwave sensor design and applications. Articles may address new insights related to sensing that are applicable to many types of analytes, or papers which report on the application of an existing sensing concept in a new way or for a new analyte. We encourage researchers from various fields within the journal's scope to contribute research articles highlighting the latest developments in their research field, or to invite relevant experts and colleagues to do the same. The topics of interest for this Special Issue include, but are not limited to:

- Microwave biosensor;
- Microwave gas sensor;
- Microwave sensor arrays;
- Quantitative microwave sensor;
- Wireless/non-contact microwave sensor;
- Microwave sensor with AI algorithm;
- Microwave sensor with ASIC chip;
- Microwave sensor with microfluidic devices;
- Microwave sensor for other applications.

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Message from the Editor-in-Chief

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